



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





High Speed Infrared Emitting Diodes, 940 nm, GaAlAs, MQW



FEATURES

- Package type: surface mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.55
- Peak wavelength: $\lambda_p = 940 \text{ nm}$
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\phi = \pm 25^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2xx3X01 and VEMT2xx3X01 series
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



DESCRIPTION

VSMB2948 series are infrared, 940 nm emitting diodes in GaAlAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- IR touch panels
- Remote control

| PRODUCT SUMMARY | | | | |
|-----------------|---------------|--------------|------------------|------------|
| COMPONENT | I_e (mW/sr) | ϕ (deg) | λ_p (nm) | t_r (ns) |
| VSMB2948RG | 20 | ± 25 | 940 | 15 |
| VSMB2948G | 20 | ± 25 | 940 | 15 |

Note

- Test conditions see table "Basic Characteristics"

| ORDERING INFORMATION | | | |
|----------------------|---------------|------------------------------|------------------|
| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
| VSMB2948RG | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Reverse gullwing |
| VSMB2948G | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Gullwing |

Note

- MOQ: minimum order quantity

| ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified) | | | | |
|---|--|------------|---------------|------------------|
| PARAMETER | TEST CONDITION | SYMBOL | VALUE | UNIT |
| Reverse voltage | | V_R | 5 | V |
| Forward current | | I_F | 100 | mA |
| Surge forward current | $t_p = 100 \mu\text{s}$ | I_{FSM} | 500 | mA |
| Power dissipation | | P_V | 160 | mW |
| Junction temperature | | T_j | 100 | $^\circ\text{C}$ |
| Operating temperature range | | T_{amb} | - 40 to + 85 | $^\circ\text{C}$ |
| Storage temperature range | | T_{stg} | - 40 to + 100 | $^\circ\text{C}$ |
| Soldering temperature | according figure 9, J-STD-020 | T_{sd} | 260 | $^\circ\text{C}$ |
| Thermal resistance junction/ambient | J-STD-051, leads 7 mm, soldered on PCB | R_{thJA} | 250 | K/W |

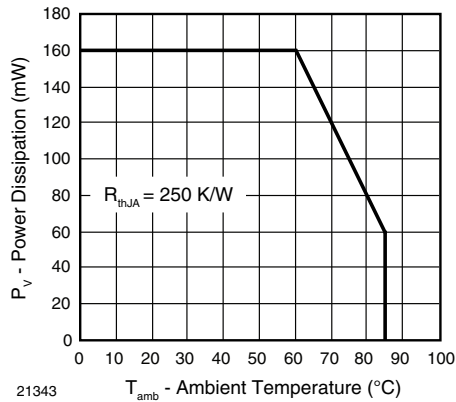


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

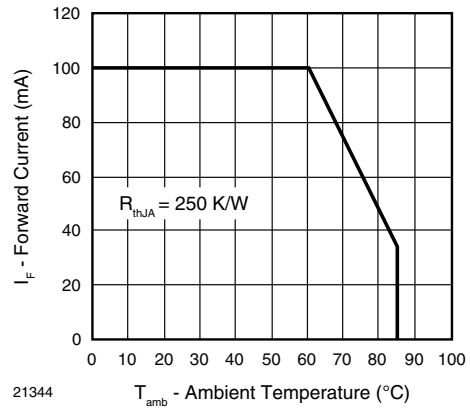


Fig. 2 - Forward Current Limit vs. Ambient Temperature

| BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified) | | | | | | |
|---|---|-----------------------------|------|-------|------|-------|
| PARAMETER | TEST CONDITION | SYMBOL | MIN. | TYP. | MAX. | UNIT |
| Forward voltage | I _F = 100 mA, t _p = 20 ms | V _F | 1.15 | 1.35 | 1.6 | V |
| | I _F = 500 mA, t _p = 100 μs | V _F | | 1.8 | | V |
| Temperature coefficient of V _F | I _F = 1 mA | TK _{V_F} | | - 1.5 | | mV/K |
| Reverse current | V _R = 5 V | I _R | | | 10 | μA |
| Junction capacitance | V _R = 0 V, f = 1 MHz, E = 0 mW/cm ² | C _J | | 21 | | pF |
| Radiant intensity | I _F = 100 mA, t _p = 20 ms | I _e | 10 | 20 | 30 | mW/sr |
| | I _F = 500 mA, t _p = 100 μs | I _e | | 90 | | mW/sr |
| Radiant power | I _F = 100 mA, t _p = 20 ms | φ _e | | 40 | | mW |
| Temperature coefficient of radiant power | I _F = 1 mA | TKφ _e | | - 1.1 | | %/K |
| Angle of half intensity | | φ | | ± 25 | | deg |
| Peak wavelength | I _F = 30 mA | λ _p | 920 | 940 | 960 | nm |
| Spectral bandwidth | I _F = 30 mA | Δλ | | 25 | | nm |
| Temperature coefficient of λ _p | I _F = 30 mA | TKλ _p | | 0.25 | | nm/K |
| Rise time | I _F = 100 mA, 20 % to 80 % | t _r | | 15 | | ns |
| Fall time | I _F = 100 mA, 20 % to 80 % | t _f | | 15 | | ns |
| Cut-off frequency | I _{DC} = 70 mA, I _{AC} = 30 mA pp | f _c | | 23 | | MHz |

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

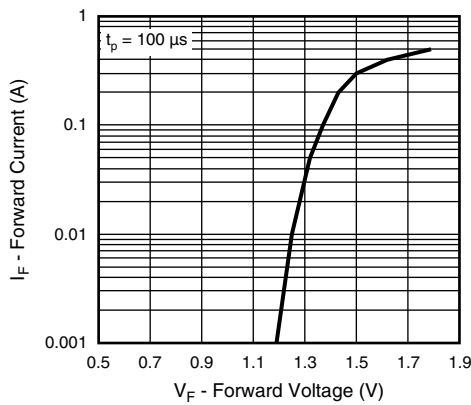


Fig. 3 - Forward Current vs. Forward Voltage

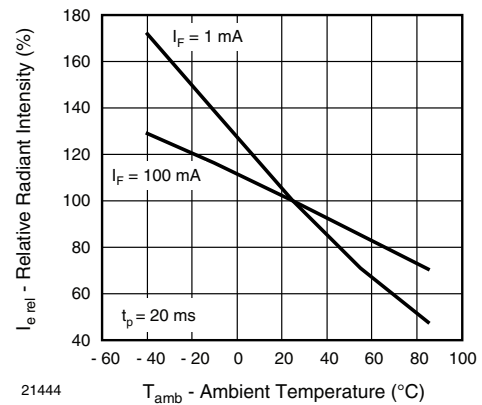


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

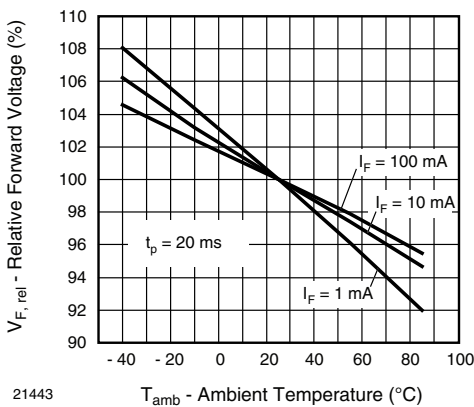


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

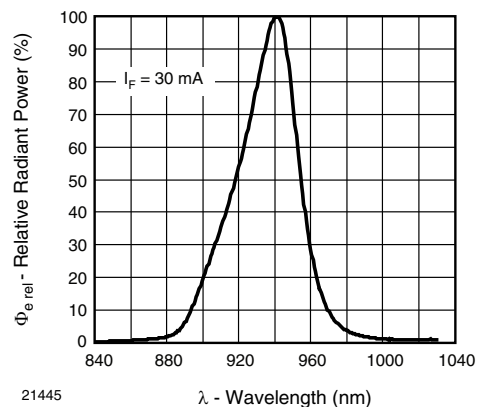


Fig. 7 - Relative Radiant Power vs. Wavelength

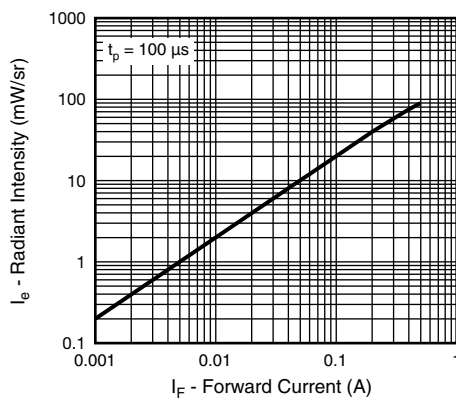


Fig. 5 - Radiant Intensity vs. Forward Current

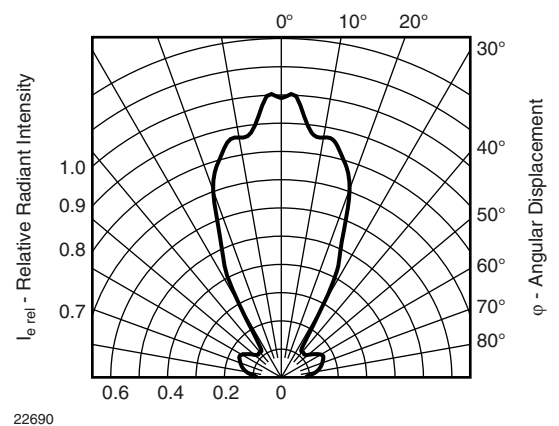


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement



SOLDER PROFILE

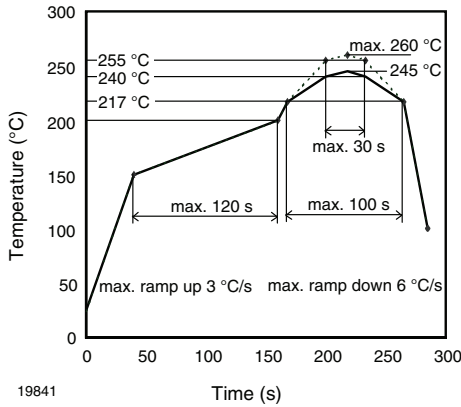


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

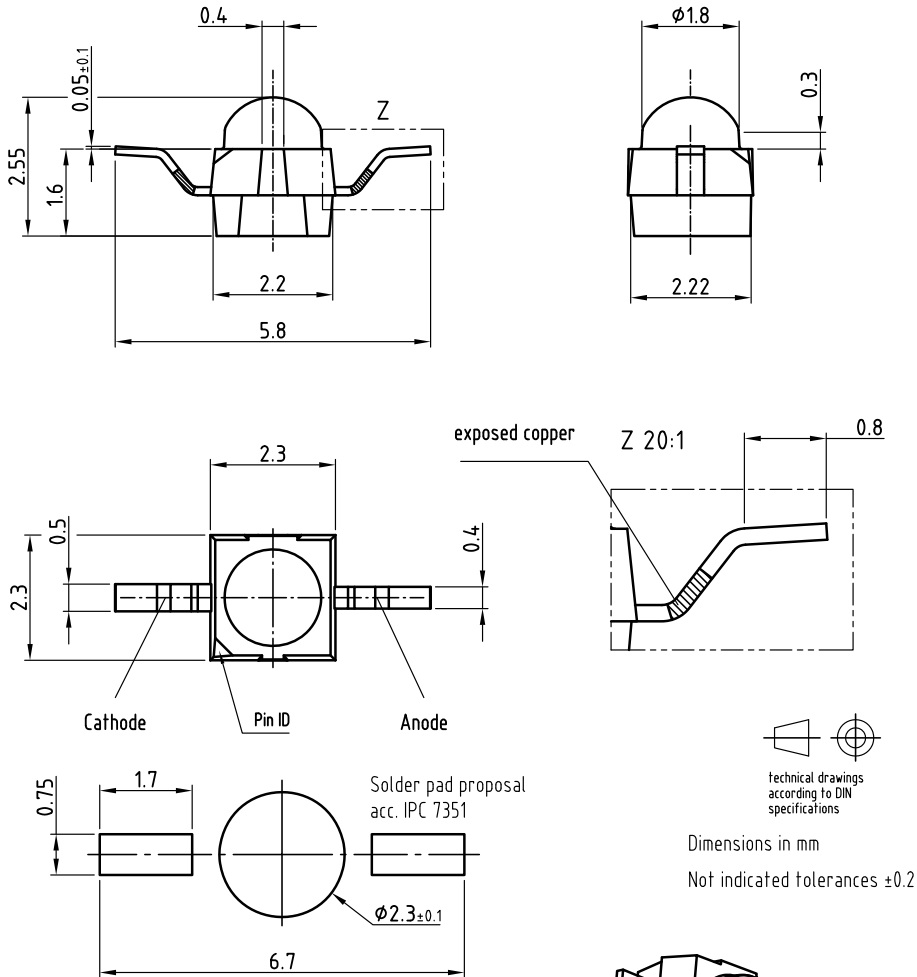
Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label.

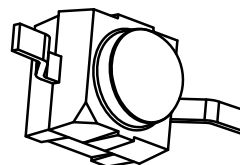
Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), $RH < 5\%$.

PACKAGE DIMENSIONS in millimeters: VSMB2948RG



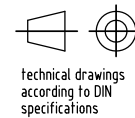
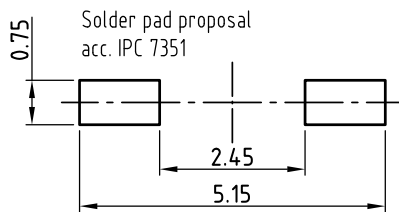
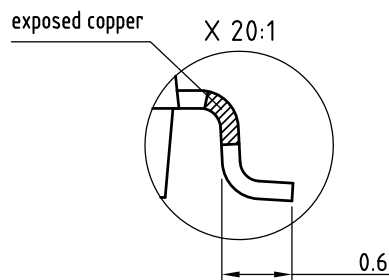
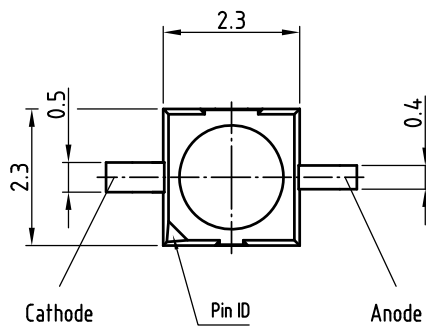
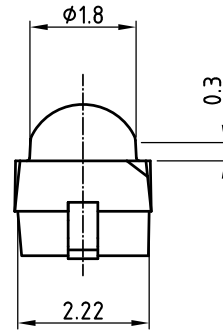
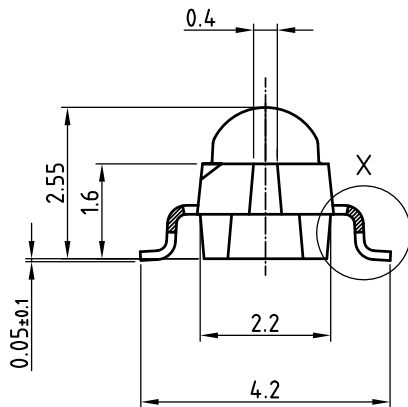
Drawing refers to following types: VSMB2943RGX01
VSMF2893RGX01
VEMD2x23X01

Drawing-No.: 6.544-5409.01-4
Issue: prel. 03.08.12





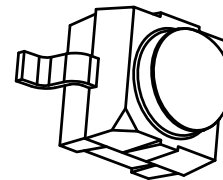
PACKAGE DIMENSIONS in millimeters: VSMB2948G



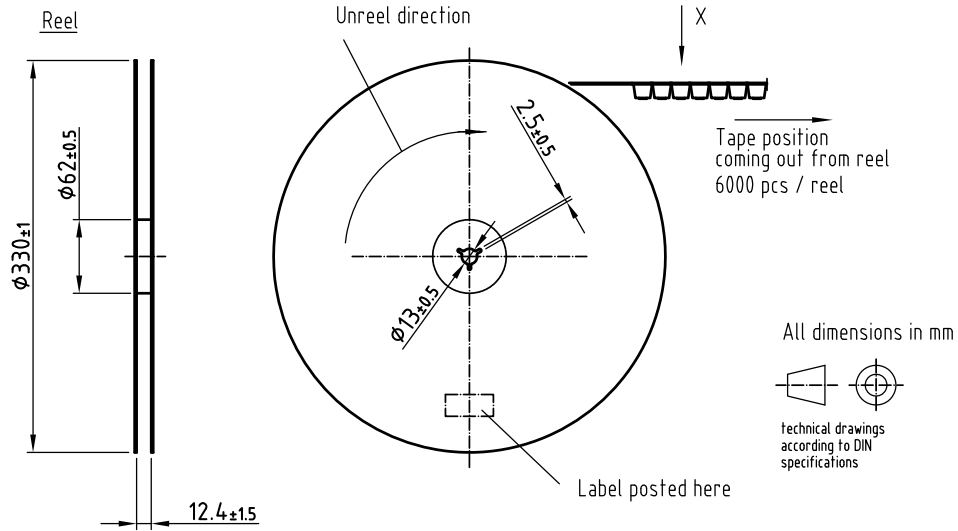
Dimensions in mm
Not indicated tolerances ±0.2

Drawing refers to following types: VSMB2943GX01
VSMF2893GX01
VEMD2x23X01

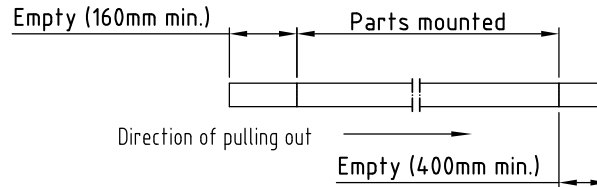
Drawing-No.: 6.544-5408.01-4
Issue: prel; 03.08.12



TAPING AND REEL DIMENSIONS in millimeters: VSMB2848RG

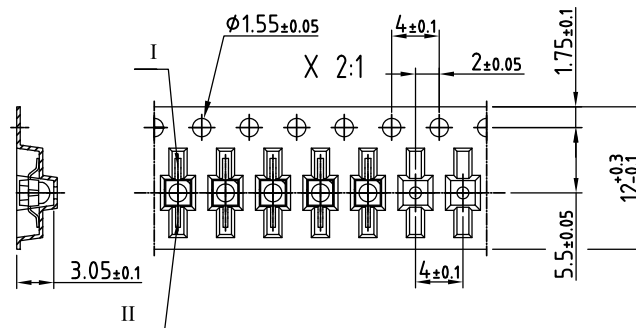


Leader and trailer tape:



Terminal position in tape

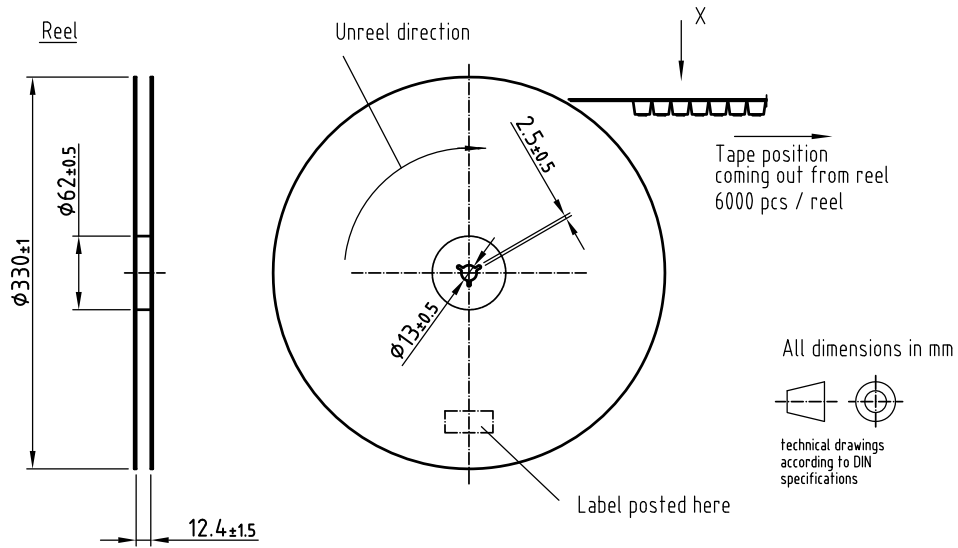
| Device | Lead I | Lead II |
|---------------|-----------|---------|
| VSMB2943RGX01 | Cathode | Anode |
| VSMF2893RGX01 | | |
| VEMD2x03X01 | | |
| VEMT2x03X01 | Collector | Emitter |
| VSMY2853RG | Anode | Cathode |



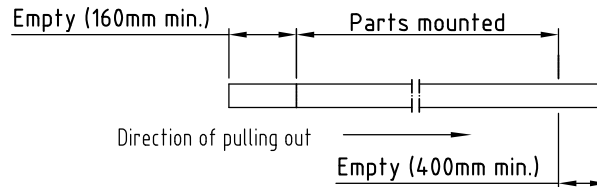
Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5100.02-4
Issue: prel; 03.08.12

TAPING AND REEL DIMENSIONS in millimeters: VSMB2848G

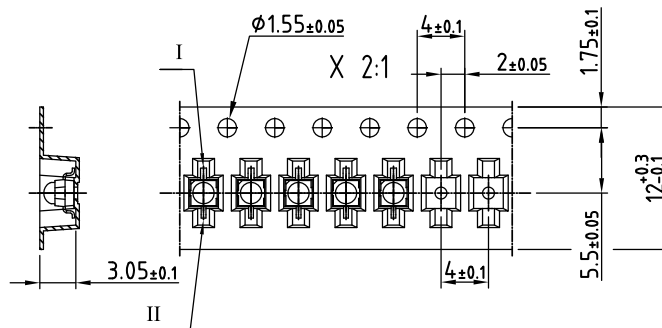


Leader and trailer tape:



Terminal position in tape

| Device | Lead I | Lead II |
|--------------|-----------|---------|
| VSMB2943GX01 | Cathode | Anode |
| VSMF2893GX01 | | |
| VEMD2x23X01 | | |
| VEMT2x23X01 | Collector | Emitter |
| VSMY2853G | Anode | Cathode |



Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5091.21-4
Issue: prel; 03.08.12



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.